

# NSR02100HT1G

## Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

### Features

- Fast Switching Speed
- Low Leakage Current
- Low Forward Voltage – 0.45 V @  $I_F = 1$  mA
- Surface Mount Device
- Low Capacitance Diode
- NSVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS

Characteristic	Symbol	Value	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	200 1.57	mW mW/ $^\circ\text{C}$
Forward Current (DC)	$I_F$	200	mA
Non-Repetitive Peak Forward Current, $t_p < 10$ msec	$I_{FSM}$	2	A
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 Minimum Pad



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## 100 VOLT SCHOTTKY BARRIER DIODE



SOD-323  
CASE 477  
STYLE 1



### MARKING DIAGRAM



JC = Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
NSR02100HT1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
NSVR02100HT1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ( $I_R = 10 \mu\text{A}$ )	$V_R$	–	100	–	V
Reverse Leakage ( $V_R = 50 \text{ V}$ )	$I_R$	–	–	0.05	$\mu\text{A}_{dc}$
Reverse Leakage ( $V_R = 100 \text{ V}$ )	$I_R$	–	–	0.15	$\mu\text{A}_{dc}$
Forward Voltage ( $I_F = 1 \text{ mA}_{dc}$ )	$V_F$	–	–	0.45	V <sub>dc</sub>
Forward Voltage ( $I_F = 10 \text{ mA}_{dc}$ )	$V_F$	–	–	0.57	V <sub>dc</sub>
Forward Voltage ( $I_F = 100 \text{ mA}_{dc}$ )	$V_F$	–	–	0.80	V <sub>dc</sub>
Forward Voltage ( $I_F = 200 \text{ mA}_{dc}$ )	$V_F$	–	–	0.95	V <sub>dc</sub>
Total Capacitance ( $V_R = 1.0 \text{ V}$ , $f = 1.0 \text{ MHz}$ )	$C_T$	–	4	10	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# NSR02100HT1G

## TYPICAL CHARACTERISTICS

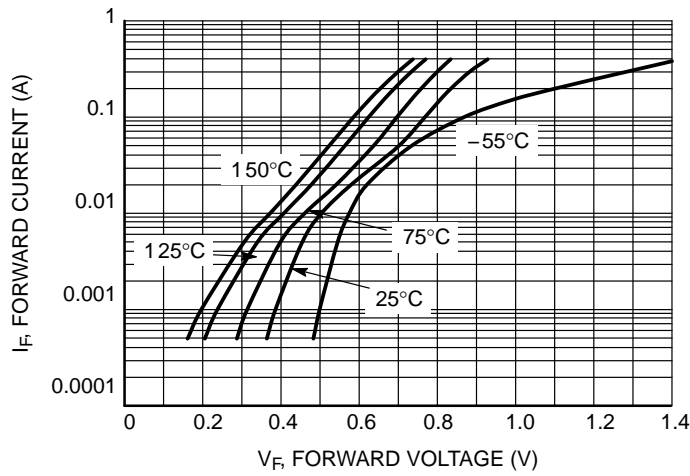


Figure 1. Forward Voltage

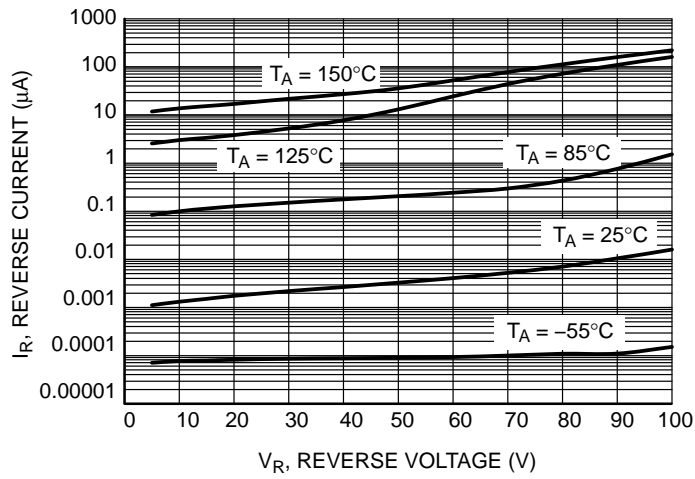


Figure 2. Leakage Current

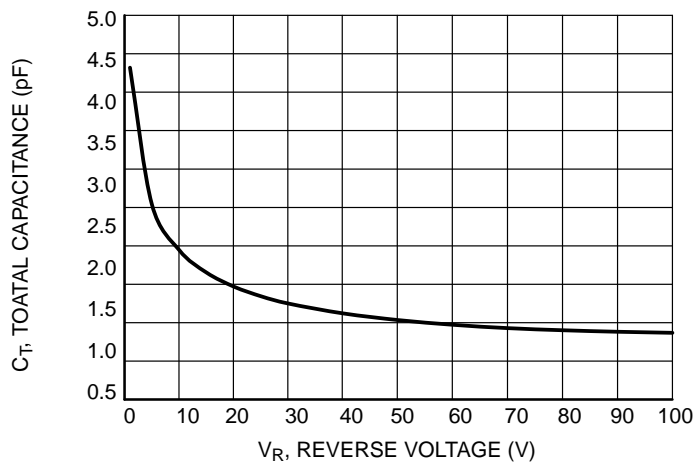
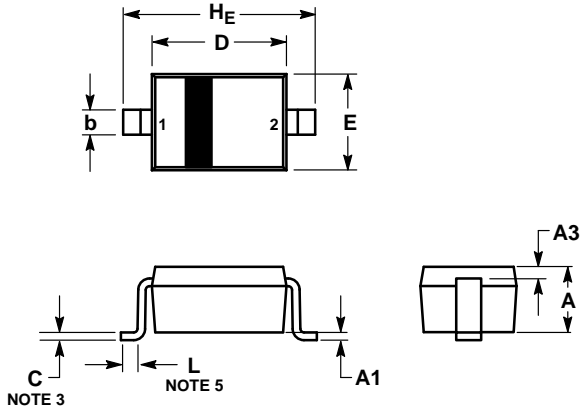


Figure 3. Total Capacitance

# NSR02100HT1G

## PACKAGE DIMENSIONS

SOD-323  
CASE 477-02  
ISSUE H

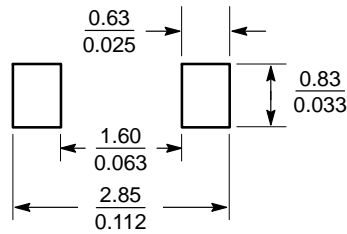


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

- STYLE 1:  
PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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